FAIRCHILD SEMICONDUCTOR®

April 2007

74ACT258
Quad 2-Input Multiplexer with 3-STATE Outputs

Features

- I_{CC} and I_{OZ} reduced by 50%
- Multiplexer expansion by tying outputs together
- Inverting 3-STATE outputs
- Outputs source/sink 24mA
- TTL-compatible inputs

General Description

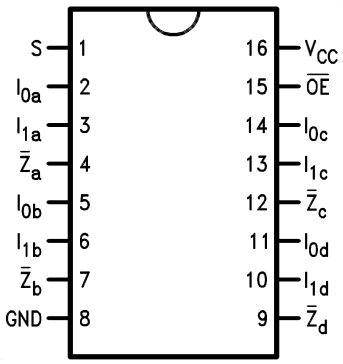
The ACT258 is a quad 2-input multiplexer with 3-STATE outputs. Four bits of data from two sources can be selected using a common data select input. The four outputs present the selected data in the complement (inverted) form. The outputs may be switched to a high impedance state with a HIGH on the common Output Enable ($\overline{OE}$) input, allowing the outputs to interface directly with bus-oriented systems.

Ordering Information

Order Number	Package Number	Package Description
74ACT258SC	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Body
74ACT258SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE 11, 5.3mm Wide
74ACT258MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

Connection Diagram



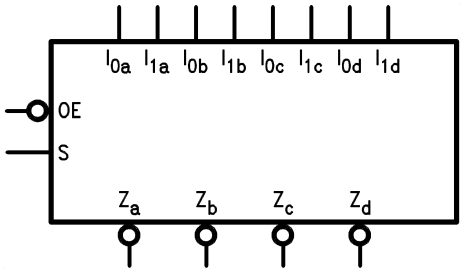
Pin Description

Pin Names	Description
S	Common Data Select Input
$\overline{OE}$	3-STATE Output Enable Input
I_{0a}–I_{0d}	Data Inputs from Source 0
I_{1a}–I_{1d}	Data Inputs from Source 1
$\overline{Z}_a$–$\overline{Z}_d$	3-STATE Inverting Data Outputs

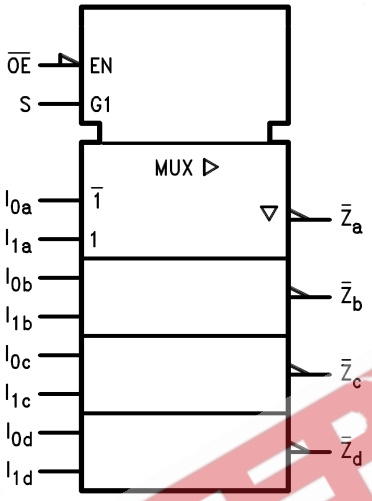
FACT™ is a trademark of Fairchild Semiconductor Corporation.

©1988 Fairchild Semiconductor Corporation

Logic Symbol



IEEE/IEC



Functional Description

The ACT258 is a quad 2-input multiplexer with 3-STATE outputs. It selects four bits of data from two sources under control of a common Select input (S). When the Select input is LOW, the I_{0x} inputs are selected and when Select is HIGH, the I_{1x} inputs are selected. The data on the selected inputs appears at the outputs in inverted form. The ACT258 is the logic implementation of a 4-pole, 2-position switch where the position of the switch is determined by the logic levels supplied to the Select input. The logic equations for the outputs are shown below:

$$\overline{Z}_a = \overline{OE} \cdot (I_{1a} \cdot S + I_{0a} \cdot \overline{S})$$
$$\overline{Z}_b = \overline{OE} \cdot (I_{1b} \cdot S + I_{0b} \cdot \overline{S})$$
$$\overline{Z}_c = \overline{OE} \cdot (I_{1c} \cdot S + I_{0c} \cdot \overline{S})$$
$$\overline{Z}_d = \overline{OE} \cdot (I_{1d} \cdot S + I_{0d} \cdot \overline{S})$$

When the Output Enable input ($\overline{OE}$) is HIGH, the outputs are forced to a high impedance state. If the outputs of the 3-STATE devices are tied together, all but one device must be in the high impedance state to avoid high currents that would exceed the maximum ratings. Designers should ensure that Output Enable signals to 3-STATE devices whose outputs are tied together are designed so there is no overlap.

Truth Table

Output Enable	Select Input	Data Inputs		Outputs
$\overline{OE}$	S	I_0	I_1	$\overline{Z}$
H	X	X	X	Z
L	H	X	L	H
L	H	X	H	L

H = HIGH Voltage Level

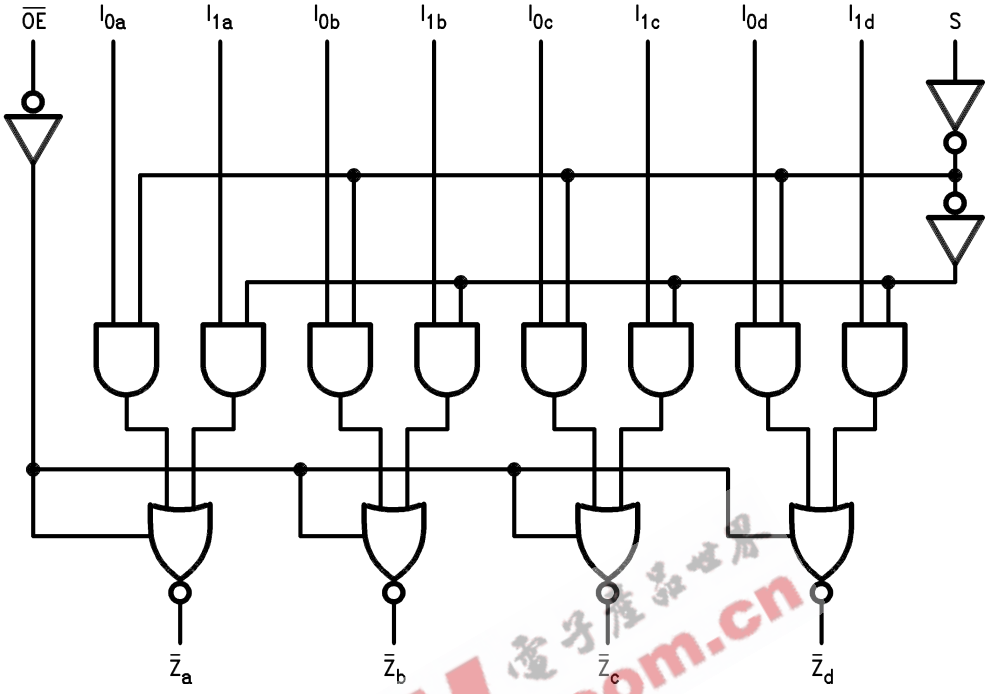
L = LOW Voltage Level

X = Immaterial

Z = High Impedance

EEPW .com.cn

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 1.

EEPW .com.cn

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	–0.5V to +7.0V
I_{IK}	DC Input Diode Current	
	$V_I = –0.5V$	–20mA
	$V_I = V_{CC} + 0.5V$	+20mA
V_I	DC Input Voltage	–0.5V to V_{CC} + 0.5V
I_{OK}	DC Output Diode Current	
	$V_O = –0.5V$	–20mA
	$V_O = V_{CC} + 0.5V$	+20mA
V_O	DC Output Voltage	–0.5V to V_{CC} + 0.5V
I_O	DC Output Source or Sink Current	±50mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current per Output Pin	±50mA
T_{STG}	Storage Temperature	–65°C to +150°C
T_J	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	4.5V to 5.5V
V_I	Input Voltage	0V to V_{CC}
V_O	Output Voltage	0V to V_{CC}
T_A	Operating Temperature	–40°C to +85°C
$\Delta V / \Delta t$	Minimum Input Edge Rate:	125mV/ns
	V_{IN} from 0.8V to 2.0V, V_{CC} @ 4.5V, 5.5V	

EEPW .com.cn

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C	T_A = –40°C to +85°C		Units
				Typ.	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage	4.5	V_{OUT} = 0.1V or V_{CC} – 0.1V	1.5	2.0	2.0	V
		5.5		1.5	2.0	2.0	
V_{IL}	Maximum LOW Level Input Voltage	4.5	V_{OUT} = 0.1V or V_{CC} – 0.1V	1.5	0.8	0.8	V
		5.5		1.5	0.8	0.8	
V_{OH}	Minimum HIGH Level Output Voltage	4.5	I_{OUT} = –50µA	4.49	4.4	4.4	V
		5.5		5.49	5.4	5.4	
		4.5	V_{IN} = V_{IL} or V_{IH}: I_{OH} = –24mA		3.86	3.76	
		5.5	I_{OH} = –24mA(1)		4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	4.5	I_{OUT} = 50µA	0.001	0.1	0.1	V
		5.5		0.001	0.1	0.1	
		4.5	V_{IN} = V_{IL} or V_{IH}: I_{OL} = 24mA		0.36	0.44	
		5.5	I_{OL}= 24mA(1)		0.36	0.44	
I_{IN}	Maximum Input Leakage Current	5.5	V_I = V_{CC}, GND		±0.1	±1.0	µA
I_{OZ}	Maximum 3-STATE Current	5.5	V_I = V_{IL}, V_{IH}; V_O = V_{CC}, GND		±0.25	±2.5	µA
I_{CCT}	Maximum I_{CC}/Input	5.5	V_I = V_{CC} – 2.1V	0.6		1.5	mA
I_{OLD}	Minimum Dynamic Output Current(2)	5.5	V_{OLD} = 1.65V Max.			75	mA
I_{OHD}		5.5	V_{OHD} = 3.85V Min.			–75	mA
I_{CC}	Maximum Quiescent Supply Current	5.5	V_{IN} = V_{CC} or GND		4.0	40.0	µA

Notes:

1. All outputs loaded; thresholds on input associated with output under test.
2. Maximum test duration 2.0ms, one output loaded at a time.

©1988 Fairchild Semiconductor Corporation

AC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)[3]	T_A = +25°C, C_L = 50pF			T_A = –40°C to +85°C, C_L = 50pF		Units
			Min.	Typ.	Max.	Min.	Max.	
t_{PLH}	Propagation Delay, I_n to $\overline{Z}_n$	5.0	2.0	6.5	8.5	1.5	9.5	ns
t_{PHL}	Propagation Delay, I_n to $\overline{Z}_n$	5.0	2.0	5.5	7.5	1.5	8.0	ns
t_{PLH}	Propagation Delay, S to $\overline{Z}_n$	5.0	3.0	7.5	10.5	2.0	11.5	ns
t_{PHL}	Propagation Delay, S to $\overline{Z}_n$	5.0	1.5	7.0	9.5	1.5	11.0	ns
t_{PZH}	Output Enable Time	5.0	2.0	6.5	8.5	1.5	9.5	ns
t_{PZL}	Output Enable Time	5.0	2.0	6.5	8.5	1.5	9.5	ns
t_{PHZ}	Output Disable Time	5.0	1.5	7.0	9.0	1.0	10.0	ns
t_{PLZ}	Output Disable Time	5.0	2.0	6.0	8.0	1.5	9.0	ns

Notes:

3. Voltage range 5.0 is 5.0V ± 0.5V.

Capacitance

Symbol	Parameter	Conditions	Typ.	Units
C_{IN}	Input Capacitance	V_{CC} = OPEN	4.5	pF
C_{PD}	Power Dissipation Capacitance	V_{CC} = 5.0V	55.0	pF

EEPW .com.cn

Physical Dimensions

Dimensions are in millimeters unless otherwise noted.

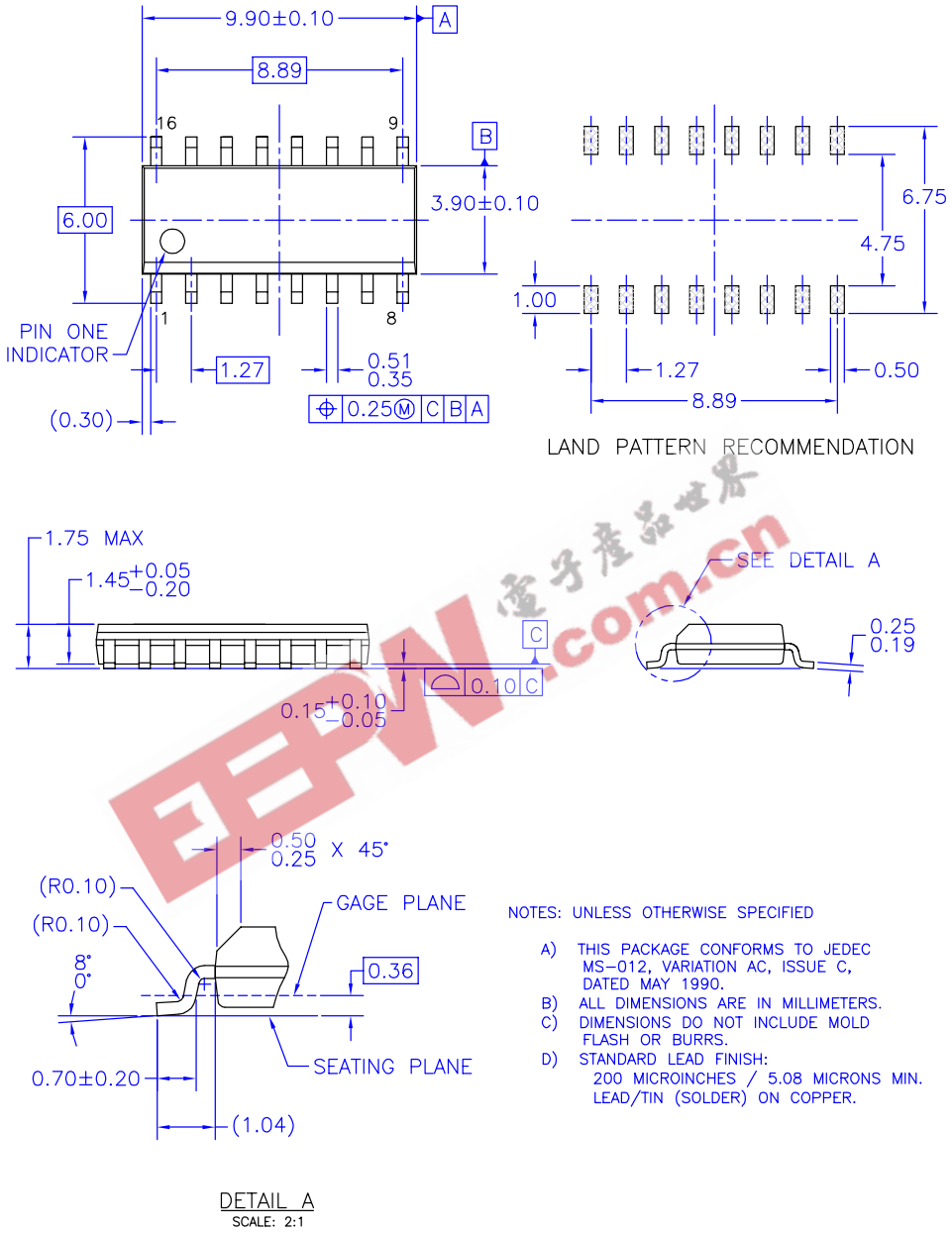
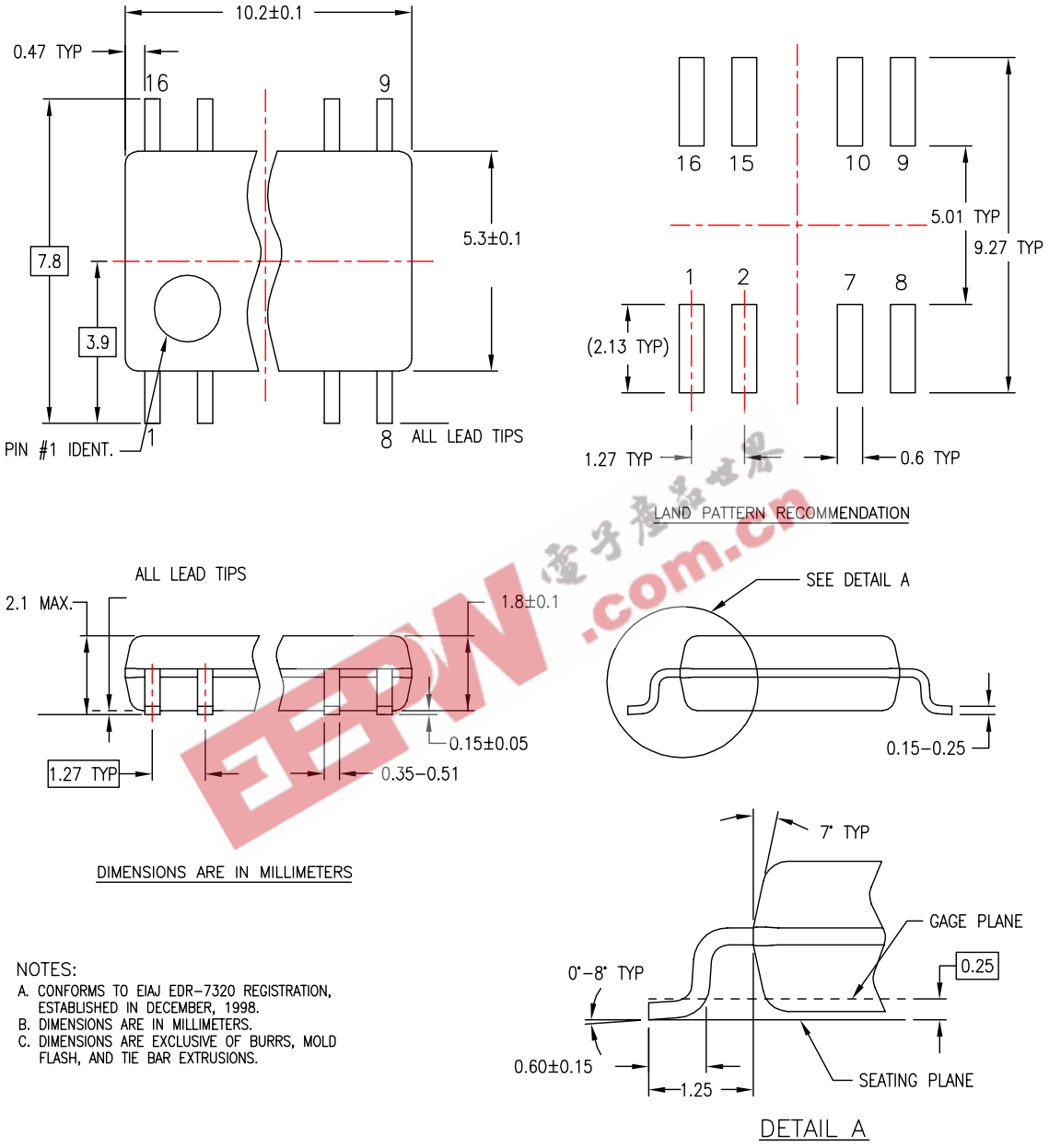


Figure 2. 16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M16A

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

A. CONFORMS TO EIAJ EDR–7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

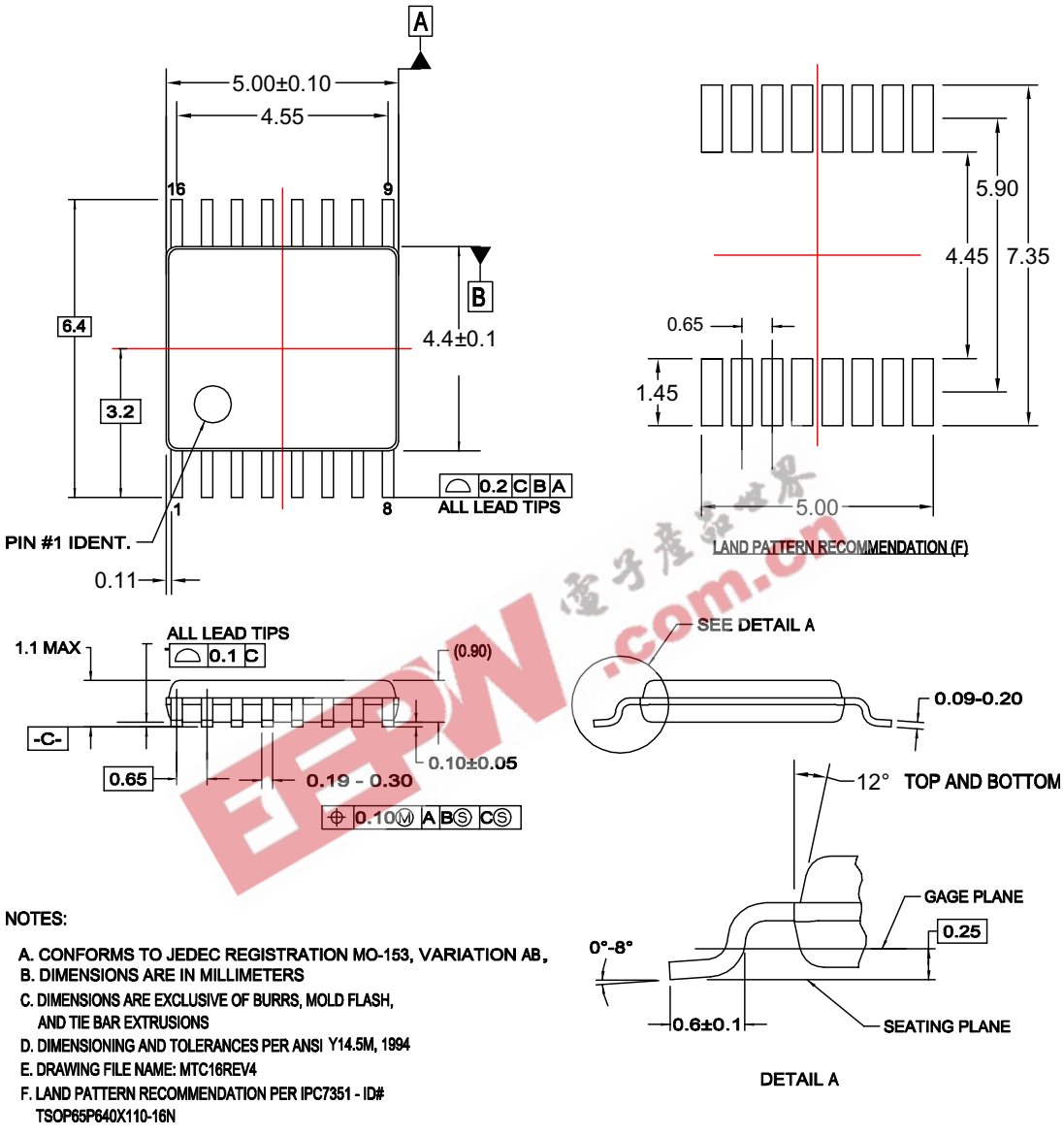
M16DREVC

Figure 3. 16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D

©1988 Fairchild Semiconductor Corporation

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB.
B. DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1994
E. DRAWING FILE NAME: MTC16REV4
F. LAND PATTERN RECOMMENDATION PER IPC7351 - ID# TSOP65P640X110-16N

MTC16rev4

Figure 4. 16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC16

©1988 Fairchild Semiconductor Corporation

FAIRCHILD SEMICONDUCTOR®

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx®
Across the board. Around the world.™
ActiveArray™
Bottomless™
Build it Now™
CoolFET™
CROSSVOLT™
CTL™
Current Transfer Logic™
DOME™
E²CMOS™
EcoSPARK®
EnSigna™
FACT Quiet Series™
FACT®
FAST®
FASTr™
FPS™
FRFET®
GlobalOptoisolator™
GTO™
HiSeC™
i-Lo™
ImpliedDisconnect™
IntelliMAX™
ISOPLANAR™
MICROCOUPLER™
MicroPak™
MICROWIRE™
MSX™
MSXPro™
OCX™
OCXPro™
OPTOLOGIC®
OPTOPLANAR®
PACMAN™
POP™
Power220®
Power247®
PowerEdge™
PowerSaver™
PowerTrench®
Programmable Active Droop™
QFET®
QS™
QT Optoelectronics™
Quiet Series™
RapidConfigure™
RapidConnect™
ScalarPump™
SMART START™
SPM®
STEALTH™
SuperFET™
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SyncFET™
TCM™
The Power Franchise®
TinyBoost™
TinyBuck™
TinyLogic®
TINYOPTO™
TinyPower™
TinyWire™
TruTranslation™
μSerDes™
UHC®
UniFET™
VCX™
Wire™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev. I24

©1988 Fairchild Semiconductor Corporation